

ABSTRACT

To provide a substrate temperature measurement apparatus and a processing apparatus, whereby thermocouple wire reliability is improved, influence of infrared ray on the chip is reduced and the temperature of the substrate can be accurately measured.

It is provided with:

a chip (16) made of metal material reflecting infrared ray or electromagnetic wave, having an inserting opening (16a) for inserting thermocouple wires (20a, 20b) which is crushed and deformed with said thermocouple wires inserted,

10 united together with said thermocouple wires , and contacted with said substrate (13); and

a supporting member or members (15b, 15c) made of material of lower thermal conductivity than said chip (16), for supporting said chip (16).